



## Product / Process Change Notice

No.: Z200-PCN-DM202510-06-A

Date: October 28, 2025

**Change Title : 2Gb (x16 SDP and x32 DDP) LPDDR4/4x technology migration of package type from WFBGA 25nm to TFBGA 20nm for industrial products.**

Change Classification:  Major  Minor with customer special request  Minor with customer notification  
Change item :  DataSheet  Design  Raw Material  Wafer FAB  Assembly  Testing  Packing   
Manufacture site  Others

***Affected Product(s) :***

Please refer to Table 1 in details.

***Description of Change(s)***

Technology migration of package type from WFBGA 25nm to TFBGA 20nm.

***Reason for Change(s) :***

According to Winbond product roadmap, launch new 2Gb LPDDR4/4X 20nm products.

***Impact of Change(s) : ( positive & negative )***

Form : Change (Please refer to attachment I)

Fit : Change (Please refer to attachment I)

Function : No Concern (Compatible between 25 nm and 20nm, Please refer to attachment II)

Reliability : No Concern (Please refer to attachment III)

Hazardous Substances: No Concern (Please refer to attachment IV and V)

***Qualification Plan/ Results :***

Based on Winbond reliability report, the new product meets our criteria and no quality concern (refer to attachment III in details)

***Implementation Plan :***

The follow-up disposition of 25nm 2Gb LPDDR4/4X.

1) The date of Last-buy orders for the 25nm 2Gb LPDDR4/4X: Apr 30, 2026

2) The last shipment date of the 25nm 2Gb LPDDR4/4X: Jul 30,2026

Date Code: \_\_\_\_ onward  Lot No: \_\_\_\_ onward  Proposed first ship date: January 30, 2026

<b>Originator:</b> (QA)	<b>H.Y. Huang</b>	<b>Approval:</b> (QA Dept. Manager)	<b>P.C. Chou</b>	<b>Approval:</b> (QRA Director)	<b>T.M. Kuo</b>	<b>Approval:</b> (Quality Center Technology Executive)	<b>W.P. CHANG</b>
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<b>Contact for Questions &amp; Concerns</b>	Name: <u>Betty Huang</u> TEL: <u>886-3-5678168</u> (ext.76549) FAX: <u>886-3-5796124</u> Address : <u>No. 8,Keya 1st Rd., Daya Dist., Central Taiwan Science Park, Taichung City 42881,Taiwan</u> E-mail: <u>Hyhuang8@winbond.com</u>
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**Customer Comments:**

*Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.*

**Major change:**  Approval       Disapproval       Conditional Approval : \_\_\_\_\_.

**Minor with customer special request:**  Approval       Disapproval       Conditional Approval : \_\_\_\_\_.

**Minor with customer notification:**  Recognition

Comment:

Date: \_\_\_\_\_

Dept. name: \_\_\_\_\_

Person in charge: \_\_\_\_\_



**Table 1. The affected part no is listed below.**

W66BP6NBUAFI	W66BP6NBUAFJ	W66BP6NBUAGI	W66BP6NBUAGJ	W66BP6NBUAHI
W66BP6NBUAHJ	W66CP2NQUADC	W66CP2NQUAFI	W66CP2NQUAFJ	W66CP2NQUAGI
W66CP2NQUAGJ	W66CP2NQUAHI	W66CP2NQUAHJ	W66BQ6NBUAFI	W66BQ6NBUAFJ
W66BQ6NBUAGI	W66BQ6NBUAGJ	W66BQ6NBUAHI	W66BQ6NBUAHJ	W66CQ2NQUAFI
W66CQ2NQUAFJ	W66CQ2NQUAGI	W66CQ2NQUAGJ	W66CQ2NQUAHI	W66CQ2NQUAHJ